Features：

- **n** Non-isolated. Mounting base as common anode cathode terminal.
- **n** Pressure contact technology with Increased power cycling capability
- **n** Low forward voltage drop

Typical Applications

- **n** Welding Power Supply
- **n** Various Dc power supplies.

V_{RRM}	Type & Outline	
800V	MD200-08-210F2NA	MD200-08-210F2NK
1000V	MD200-10-210F2NA	MD200-10-210F2NK
1200V	MD200-12-210F2NA	MD200-12-210F2NK
1400V	MD200-14-210F2NA	MD200-14-210F2NK
1600V	MD200-16-210F2NA	MD200-16-210F2NK
1800V	MD200-18-210F2NA	MD200-18-210F2NK

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, T_C=100°C	150			200	A
$I_{F(RMS)}$	RMS forward current					314	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			8	mA
I_{FSM}	Surge forward current	V_R=60%V_{RRM}, t=10ms half sine	150			6.2	kA
I^2t	I^2t for fusing coordination					192	10^3A^2s
V_{FO}	Threshold voltage		150			0.80	V
r_F	Forward slope resistance					0.96	mΩ
V_{FM}	Peak forward voltage	I_{FM}=600A	25			1.50	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.20	°C/W
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.10	°C/W
F_m	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T_{vj}	Junction temperature			-40		150	°C
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				185		g
Outline	210F2NA, 210F2NK						

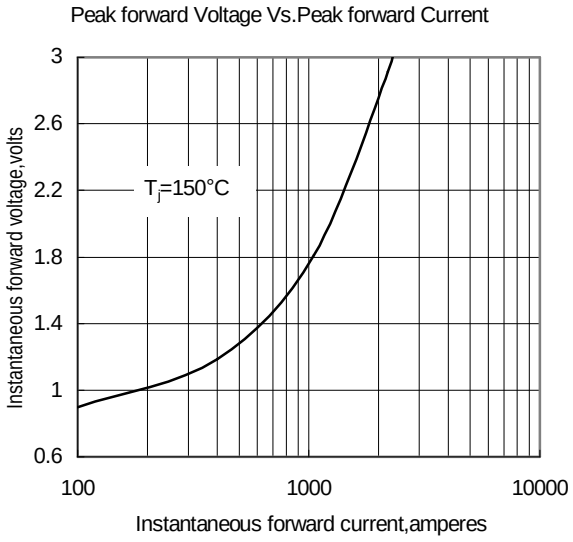


Fig.1

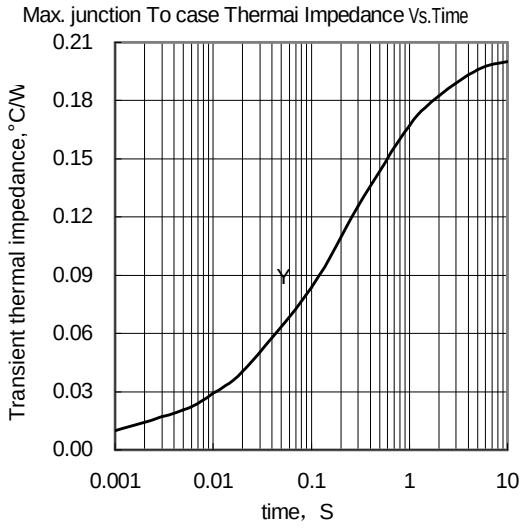


Fig.2

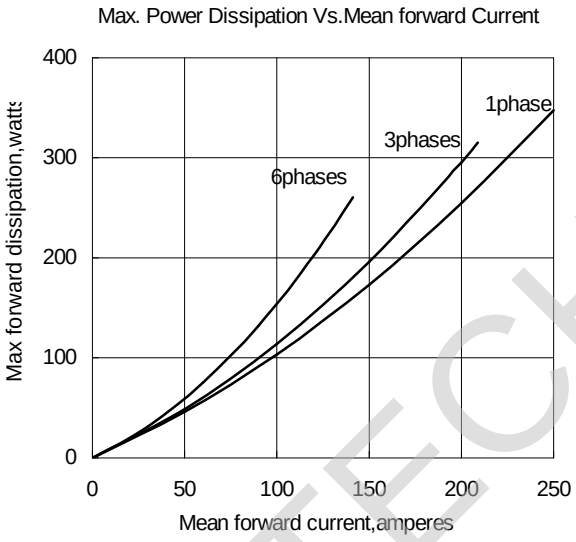


Fig.3

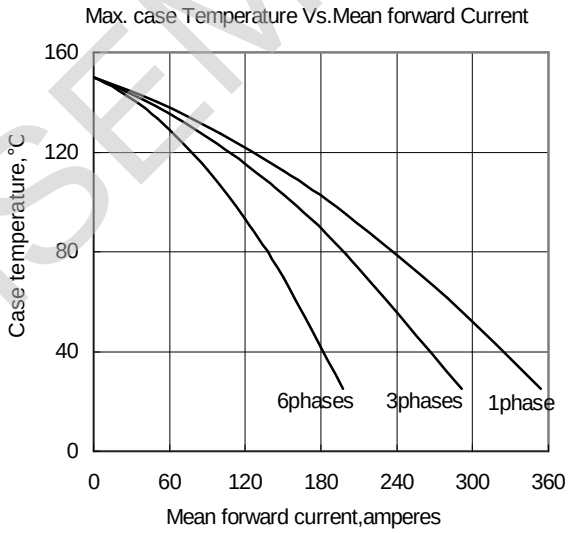


Fig.4

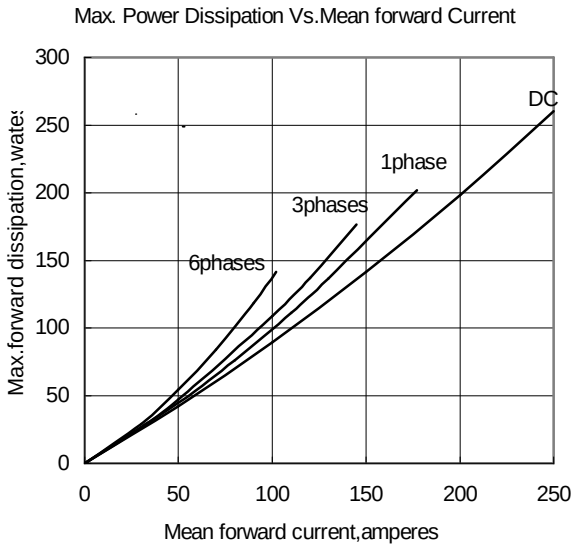


Fig.5

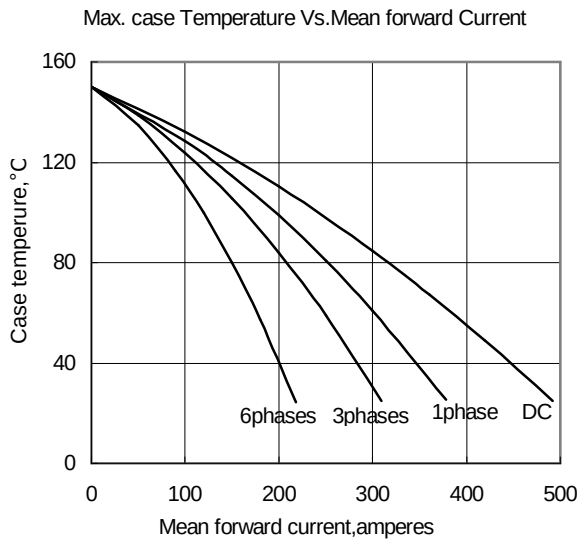


Fig.6

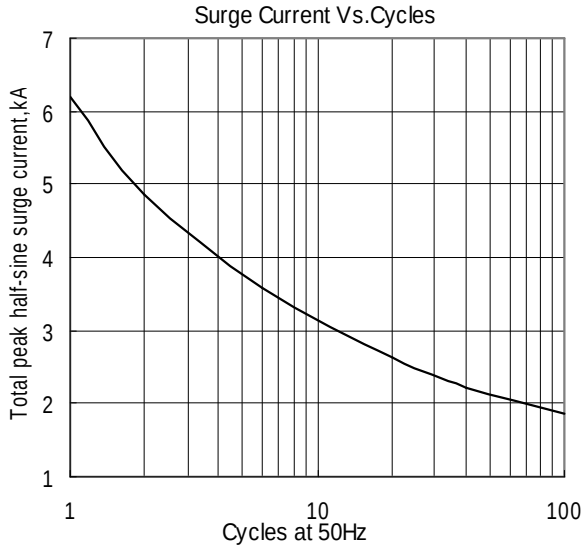


Fig.7

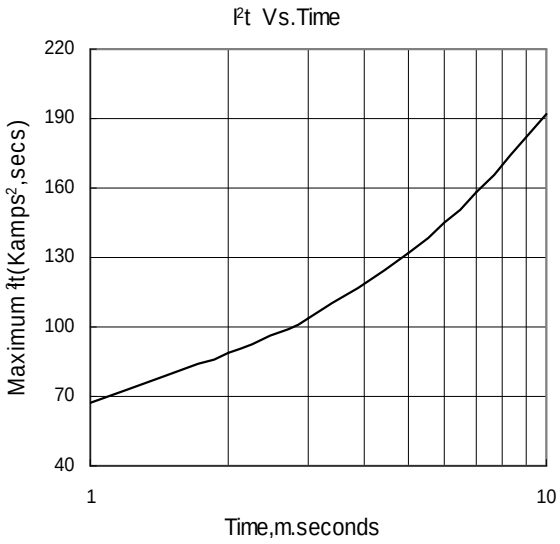
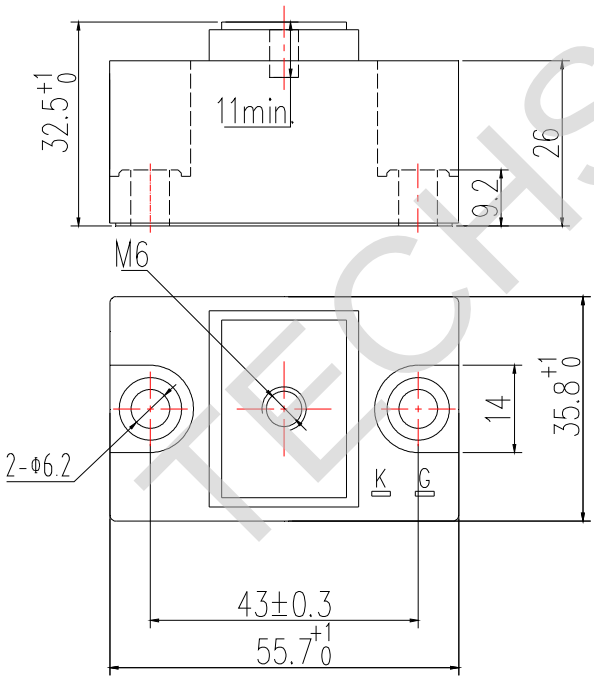
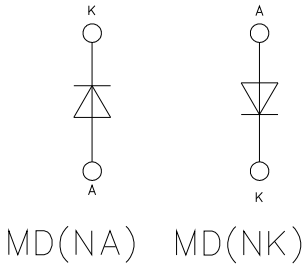


Fig.8

Outline:





Unmarked dimensional tolerance：±0.5mm